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**THE**  
PARTNER  
FOR CUSTOMIZED WET PROCESS  
EQUIPMENT



## SpinStep *Flex line*

The modular, versatile single wafer system SpinStep *Flex line* is designed for etching, cleaning, lift-off, coating and developing

## BENEFITS

- > Modular design
- > Customizable and extensible (i.e. semi- to fully automation, adaption of second process bowl)
- > Different chemical supply systems are available
- > Different processes in one bowl possible
- > Easy to change the wafer size
- > Optimized footprint
- > Two tool sizes are available (Tool size 1: up to 200mm wafer, tool size 2: from 200 to 300mm wafers and substrates)
- > User friendly and easy to use; operation and tool control via 15" touchpanel



## APPLICATIONS

The SpinStep *Flex line* is designed for the following processes:

Semiconductor – Clean:

SC1, SC2, Piranha, DIW, Post CMP clean, DO-O3

Semiconductor – Etch:

Etch/Siliziumoxid (Clean), Etch/Siliziumoxid, Etch Silizium

Semiconductor – Lift-off:

Our new patent pending lift-off process

Semiconductor – Coating and developing:

Positiv – negativ spray / puddle coating and developing

Semiconductor – Mask processor:

Cleaning, coating and developing



### Mini Chemical Management System

- > Mini Chemical Delivery System (MCDS)
- > Mini Chemical Waste System (MCWS)
- > Mini Chemical Mixing System (MCMS)
- > Mini Chemical Recirculation System (MCRS)
- > Mini Chemical Spiking System (MCSS)

### Options

- > Megasonic system (MEGPie, Nozzle)
- > Highpressure system
- > Single side brush
- > Mixing nozzles
- > Puddle nozzles
- > Pre-Soak
- > Chamber rinse
- > Media heating system
- > Programmable dispense arms
- > Drain separation system
- > Fire suppression system
- > SECS II GEM Interface
- > FM 4910 compliant
- > Vacuum, low contact chuck
- > Backside protection chuck
- > Cool- Hot-plate stacks
- > HMDS primer module